

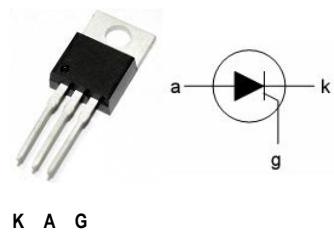
## **BT151**

### **Thyristors**

#### **General Description**

- ◆ Package: TO-220AB
- ◆ Glass passivated thyristors in a plastic envelope, Intended for use in applications requiring high bidirectional blocking voltage capability and high thermal cycling performance. Typical applications include motor control ,industrial and domestic lighting,heating and static switching.

#### DRAWING



#### **Limiting Values**

##### **Limiting values in accordance with the absolute Maximum System(IEC134)**

SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
$V_{DRM}, V_{RRM}$	Repetitive peak off-state Voltages			600	V
$I_{T(AV)}$	Average on-state current	half sine wave; $T_{mb} \leq 109^\circ C$		7.5	A
$I_{T(RMS)}$	RMS on-state current	all conduction angles		12	A
$I_{TSM}$	Non-repetitive peak on-state current	half sine wave; $T_j = 25^\circ C$ prior to surge			
		$t = 10ms$		100	A
		$t = 8.3ms$		110	A
$I^2T$	$I^2T$ for fusing	$t = 10ms$		50	$A^2S$
$Dit/dt$	Repetitive rate of rise of on-state current after triggering	$I_{TM} = 20A; IG = 50mA; DiG/dt = 50mA/us$		50	A/us
$I_{GM}$	Peak gate current			2	A
$V_{gm}$	Peak gate voltage			5	V
$V_{RGM}$	Peak reverse gate voltage			5	V
$P_{GM}$	Peak gate power			5	W
$P_{G(AV)}$	Average gate power	over any 20 ms period		0.5	W
$T_{STG}$	Storage temperature		-40	150	$^\circ C$
$T_j$	Operating junction temperature			125	$^\circ C$

#### **Thermal Resistances**

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
$R_{thj-mb}$	Thermal resistance junction to mounting base				1.3	K/W
$R_{thj-a}$	Thermal resistance junction to ambient			60		K/W

### Static Characteristics

T<sub>j</sub>=25°C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
I <sub>GT</sub>	Gate trigger current	V <sub>D</sub> =12V;I <sub>T</sub> =0.1A		2	15	mA
I <sub>L</sub>	Latching current	V <sub>D</sub> =12V;I <sub>GT</sub> =0.1A		10	40	mA
I <sub>H</sub>	Holding current	V <sub>D</sub> =12V;I <sub>GT</sub> =0.1A		7	20	mA
V <sub>T</sub>	On-state voltage	I <sub>T</sub> =23A		1.4	1.75	V
V <sub>GT</sub>	Gate trigger voltage	V <sub>D</sub> =12V;I <sub>T</sub> =0.1A		0.6	1.5	V
		V <sub>D</sub> =V <sub>DRM(MAX)</sub> ;I <sub>T</sub> =0.1A;T <sub>j</sub> =125°C	0.25	0.4		V
I <sub>D</sub> ,I <sub>R</sub>	Off-state leakage current	V <sub>D</sub> =V <sub>DRM(MAX)</sub> ;V <sub>R</sub> =V <sub>RRM(MAX)</sub> ;T <sub>j</sub> =125°C		0.1	0.5	mA

### Dynamic Characteristics

T<sub>j</sub>=25°C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
DVD/dt	Critical rate of rise or off-state voltage	VDM=67%VDRM(MAX);TJ=125°C; exponential waveform;				
		Gate open circuit	50	130		V/us
		RGK=100Ω	200	1000		V/us
tgt	Gate controlled turn-on time	ITM=40A;VD=VDRM(MAX);IG=0.1A		2		us
		Dig/dt=5A/us				
tq	Circuit commutated turn-off time	VD=67%VDRM(MAX);TJ=125°C		70		us
		ITM=20A;VR=25V;Ditm/dt=30A/us				
		dvd/dt=50V/us;Rgk=100Ω				

### Typical Characteristics

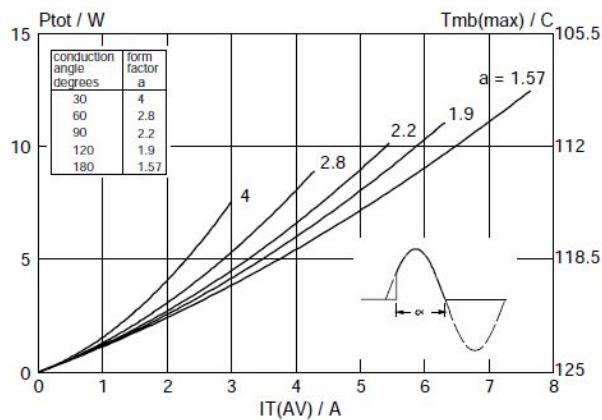


Fig.1. Maximum on-state dissipation,  $P_{tot}$ , versus average on-state current,  $I_{T(AV)}$ , where  $a$  = form factor =  $I_{T(RMSY)} / I_{T(AV)}$ .

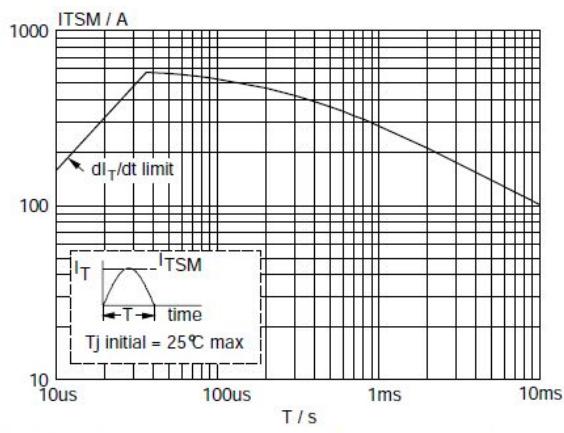


Fig.2. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$  versus pulse width  $t_p$  for sinusoidal currents,  $t_p \leq 10ms$ .

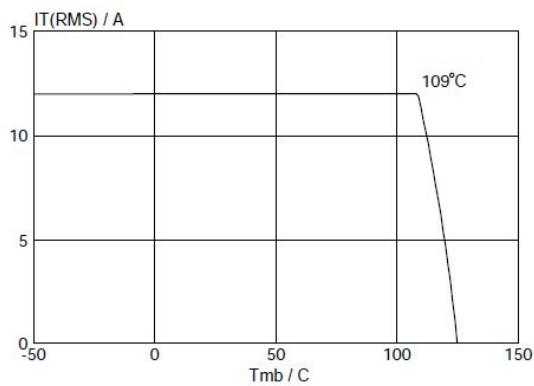


Fig.3. Maximum permissible rms current  $I_{T(RMS)}$  versus mounting base temperature  $T_{mb}$ .

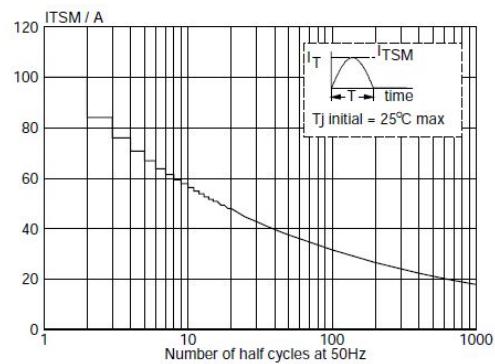


Fig.4. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus number of cycles, for sinusoidal currents,  $f = 50$  Hz.

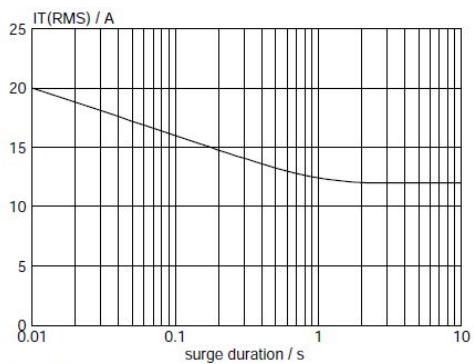


Fig.5. Maximum permissible repetitive rms on-state current  $I_{T(RMS)s}$ , versus surge duration, for sinusoidal currents,  $f = 50$  Hz;  $T_{mb} \leq 109^\circ\text{C}$ .

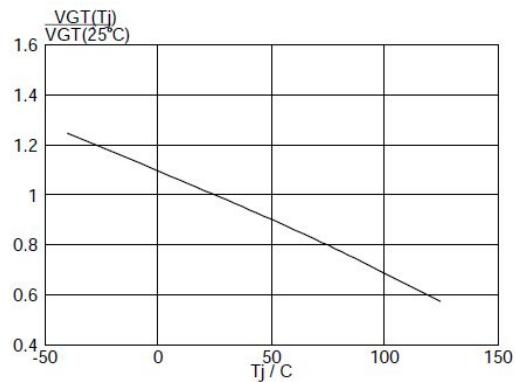


Fig.6. Normalised gate trigger voltage  $V_{GT}(T_j)/V_{GT}(25^\circ\text{C})$ , versus junction temperature  $T_j$ .

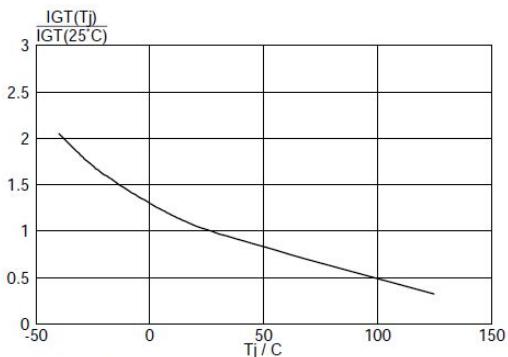


Fig.7. Normalised gate trigger current  $I_{GT}(T_j)/I_{GT}(25^\circ\text{C})$ , versus junction temperature  $T_j$ .

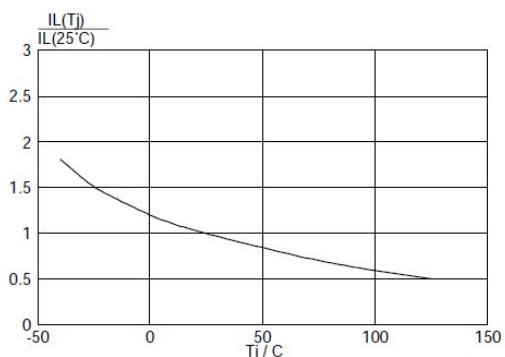


Fig.8. Normalised latching current  $I_L(T_j)/I_L(25^\circ\text{C})$ , versus junction temperature  $T_j$ .

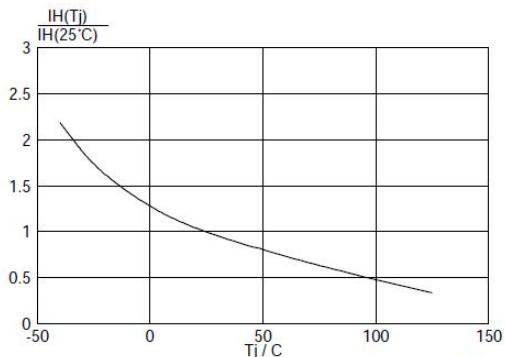


Fig.9. Normalised holding current  $I_H(T_j)/I_H(25^\circ\text{C})$ , versus junction temperature  $T_j$ .

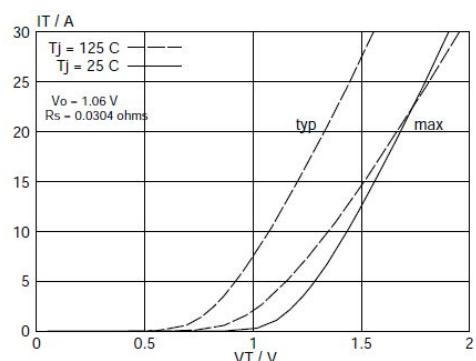


Fig.10. Typical and maximum on-state characteristic.

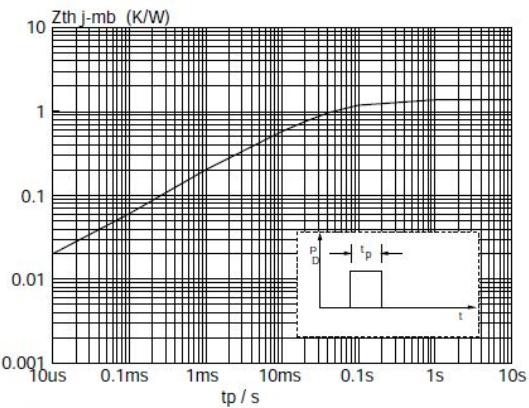


Fig.11. Transient thermal impedance  $Z_{th,j-mb}$  versus pulse width  $t_p$ .

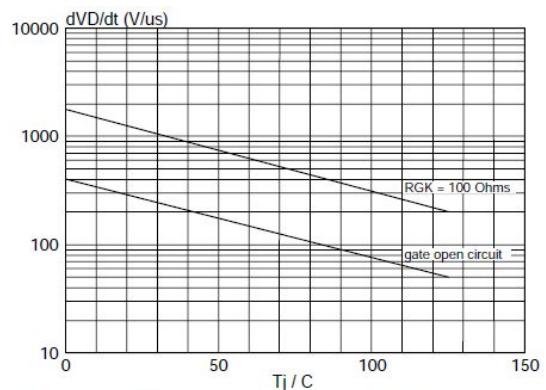


Fig.12. Typical, critical rate of rise of off-state voltage,  $dV_D/dt$  versus junction temperature  $T_j$ .

#### Mechanical Dimensions

